

ADG5208 and ADG5209 LFCSP Redesign Qualification

QUALIFICATION RESULT			
TEST	SPECIFICATION	SAMPLE SIZE	RESULT
Solder Heat Resistance Test (SHR)*	JEDEC/IPC <i>J-STD-020</i>	1 x 30	PASS
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	1 x 77	PASS
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JS-001</i>	3/voltage	PASS ±2500V
Electrostatic Discharge <i>Machine Body Model</i>	JEDEC <i>JESD22-A115</i>	3/voltage	PASS ±400V
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	PASS ±1250V

*Preconditioned per JEDEC/IPC J-STD-020

**ADG5208 and ADG5209 LFCSP Redesign
Resulting in Datasheet Specification Changes**

4x4mm LFCSP at STATS ChipPAC China

QUALIFICATION RESULT			
TEST	SPECIFICATION	SAMPLE SIZE	RESULT
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	PASS
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 77	PASS
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77	PASS
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	PASS

*Preconditioned per JEDEC/IPC J-STD-020

2um HV CMOS Process at AD Limerick

QUALIFICATION RESULT			
TEST	SPECIFICATION	SAMPLE SIZE	RESULT
High Temperature Operating Life (HTOL)*	JEDEC <i>JESD22-A108</i>	9 x 77	PASS
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	9 x 77	PASS
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	3 x 49	PASS

*Preconditioned per JEDEC/IPC J-STD-020